



Material Content Data Sheet



Sales Product Name		BGS 22WL10 E6327		Issued		20. July 2018		
MA#		MA001052370						
Package		PG-TSLP-10-1		Weight*		1.46 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.563	38.67	38.67	386730	386730
bumps	non noble metal	copper	7440-50-8	0.011	0.78	0.78	7799	7799
leadframe	non noble metal	nickel	7440-02-0	0.141	9.70	9.70	96981	96981
encapsulation	organic material	carbon black	1333-86-4	0.003	0.24		2382	
	plastics	epoxy resin	-	0.101	6.91		69062	
	inorganic material	silicondioxide	60676-86-0	0.589	40.47	47.62	404845	476289
leadfinish	noble metal	gold	7440-57-5	0.015	1.00	1.00	9978	9978
plating	noble metal	silver	7440-22-4	0.024	1.63	1.63	16294	16294
ubm	non noble metal	titanium	7440-32-6	0.001	0.04		377	
	non noble metal	tungsten	7440-33-7	0.000	0.02		197	
	non noble metal	copper	7440-50-8	0.002	0.11	0.17	1065	1639
solder	noble metal	silver	7440-22-4	0.000	0.01		99	
	non noble metal	tin	7440-31-5	0.006	0.42	0.43	4191	4290
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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